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ON Semiconductor®

## **FDD5N50**

# N-Channel UniFET<sup>TM</sup> MOSFET 500 V, 4 A, 1.4 $\Omega$

#### **Features**

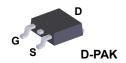
- $R_{DS(on)}$  = 1.15  $\Omega$  (Typ.) @  $V_{GS}$  = 10 V,  $I_D$  = 2 A
- Low Gate Charge (Typ. 11 nC)
- Low C<sub>rss</sub> (Typ. 5 pF)
- · 100% Avalanche Tested
- RoHS Compliant

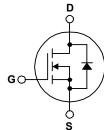
## **Applications**

- LCD/LED/PDP TV
- Lighting
- · Uninterruptible Power Supply

## **Description**

UniFET<sup>TM</sup> MOSFET is ON Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





## **MOSFET Maximum Ratings** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol		Parameter		FDD5N50TM-WS	Unit
$V_{DSS}$	Drain to Source Voltage			500	V
$V_{GSS}$	Gate to Source Voltage			±30	V
	Drain Current	- Continuous (T <sub>C</sub> = 25°C)		4	А
ID	Drain Current	- Continuous (T <sub>C</sub> = 100°C)		2.4	_ A
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	16	Α
E <sub>AS</sub>	Single Pulsed Avalanche	Energy	(Note 2)	256	mJ
I <sub>AR</sub>	Avalanche Current		(Note 1)	4	Α
E <sub>AR</sub>	Repetitive Avalanche Ene	ergy	(Note 1)	4	mJ
dv/dt	Peak Diode Recovery dv/	'dt	(Note 3)	4.5	V/ns
n	Dower Dissinction	(T <sub>C</sub> = 25°C)		40	W
$P_{D}$	Power Dissipation	- Derate Above 25°C		0.3	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Te	emperature Range		-55 to +150	°C
TL	Maximum Lead Tempera	ture for Soldering, 1/8" from Case f	or 5 Seconds	300	°C

#### **Thermal Characteristics**

Symbol	Parameter	FDD5N50TM-WS	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	1.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	110	- 0/00

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDD5N50TM-WS	FDD5N50	DPAK	Tape and Reel	330 mm	16 mm	2500 units

**Test Conditions** 

Min.

Тур.

Max.

Unit

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted. Parameter

Off Chara	acteristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_J = 25^{\circ} C$	500	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C	-	0.6	-	V/°C
	/oro (2sto Voltage I)rain (Current	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	-	-	1	^
IDSS		$V_{DS} = 400 \text{ V}, T_C = 125^{\circ}\text{C}$	-	-	10	μΑ
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

#### On Characteristics

Symbol

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	3.0	-	5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$	-	1.15	1.4	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 2 \text{ A}$	-	4.3	-	S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 05.V.V 0.V	-	480	640	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	66	88	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12	-	5	8	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 5 A,	-	11	15	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	3	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	(Not	e 4) _	5	-	nC

## **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		-	13	36	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 250 \text{ V}, I_D = 5 \text{ A},$	-	22	54	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_G$ = 25 $\Omega$	-	28	66	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	20	50	ns

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	4	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	16	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 4 A	-	-	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 5 A,	-	300	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 100 A/μs	-	1.8	-	μС

- 1: Repetitive rating: pulse-width limited by maximum junction temperature.
- 2: L = 32 mH,  $I_{AS}$  = 4 A,  $V_{DD}$  = 50 V,  $R_G$  = 25  $\Omega$ , starting  $T_J$  = 25°C.
- 3:  $I_{SD} \le 4$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le BV_{DSS}$ , starting  $T_J = 25^{\circ}C$ .
- 4: Essentially independent of operating temperature typical characteristics.

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

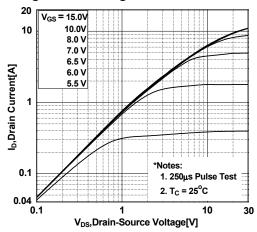
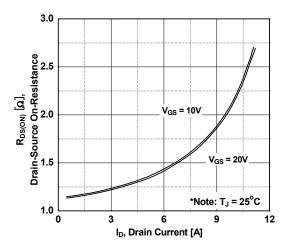


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage



**Figure 5. Capacitance Characteristics** 

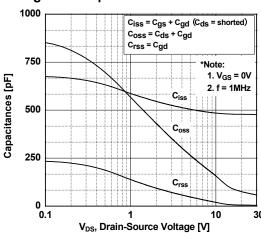


Figure 2. Transfer Characteristics

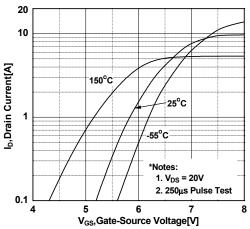


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

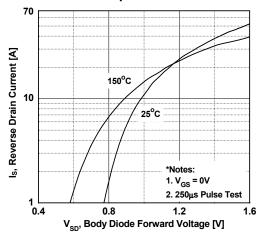
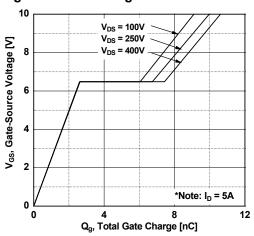


Figure 6. Gate Charge Characteristics



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

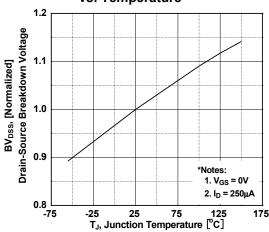


Figure 8. On-Resistance Variation vs. Temperature

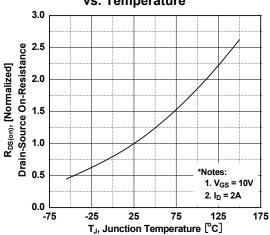


Figure 9. Maximum Safe Operating Area

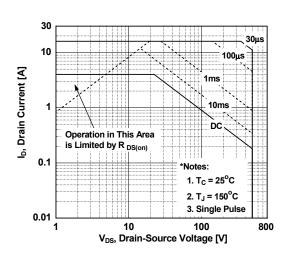


Figure 10. Maximum Drain Current vs. Case Temperature

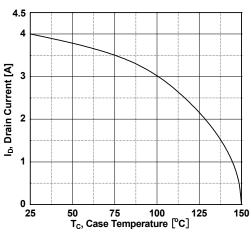
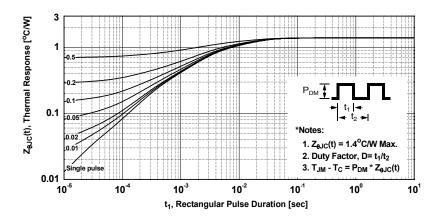


Figure 11. Transient Thermal Response Curve



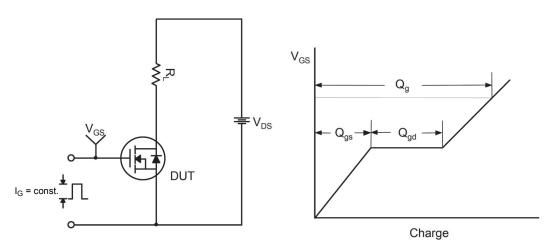


Figure 12. Gate Charge Test Circuit & Waveform

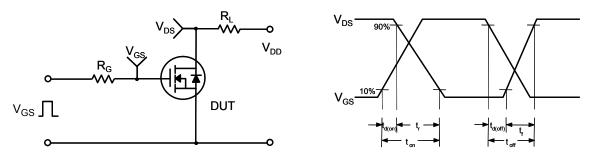


Figure 13. Resistive Switching Test Circuit & Waveforms

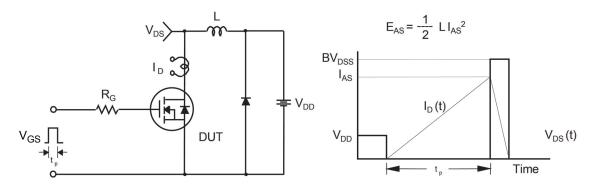
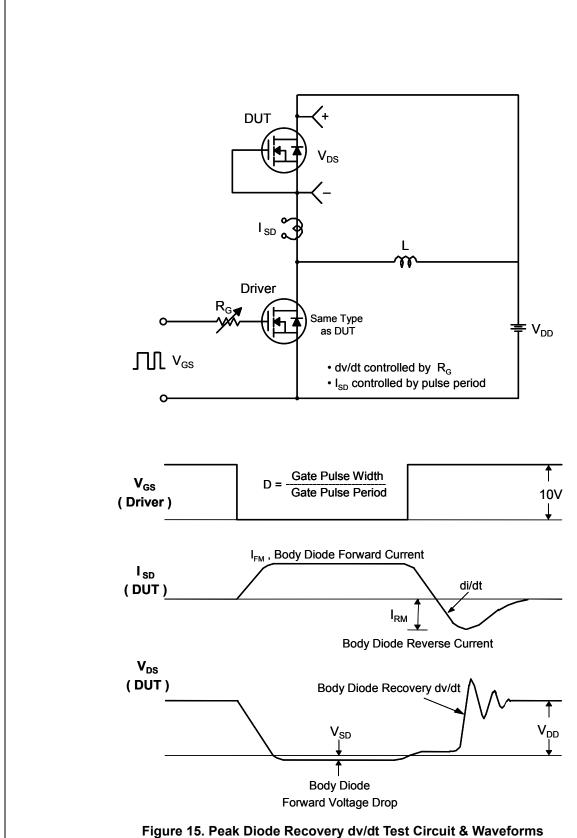


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



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#### **Mechanical Dimensions**

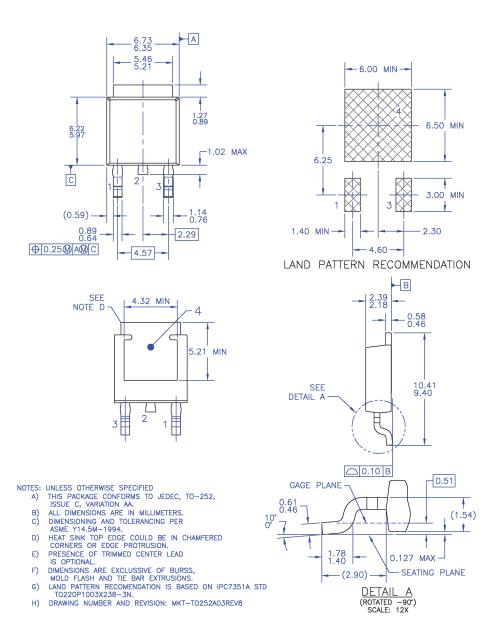


Figure 16. TO252 (D-PAK), Molded, 3-Lead, Option AA&AB

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